



# **i-PULSE** \$10/\$20

## 3D Hybrid Modular Mounter

S10 spec

Max. board size **1,330 x 510 mm** (option)

**O201 to 120 x 90 mm** (option)

90 lanes (8 mm tape conversion)

Machine width
1.250 mm

S20 spec

Max. board size **1,830 x 510 mm** (option)

Applicable components **0201 to 120 x 90 mm** (option)

Feeder capacity **180 lanes** (8 mm tape conversion)

Machine width 1,750 mm



### **Production Revolution**

### **Ultimate flexibility**

#### Color fiducial camera

A newly developed color camera and illumination system ensure robust dispense dot verification.



### New head unit for higher speed placement

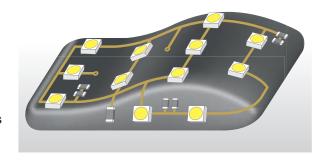
Our 12-axis 2-theta head has been redesigned for high speed placement but was built to accommodate large component placement as well. The new design also makes the 12 axis head extremely effective at high speed LED placement.



▲ 12-axis 2-theta head unit

### **Enhancement to 3D MID**

The S10 and S20 offer dispense and placement capabilities on standard PCB applications but will also offer optional functionality for irregular PCB's such as: concave/convexed, tilted and curved surfaces. To ensure the S Series will be ready for 3D MID (Molded Interconnect Devices) production, the machines have preconfigured XY structures that will allow for upgrades to build 3D MID applications for automotive, medical and telecommunications requirements of the future.



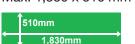
## Max. feeder capacity 180 lanes

The S20 can accommodate max. 180 feeders (45 lanes x 4 positions, 8 mm tape conversion). The S10 can accommodate max. 90 feeders (45 lanes x 2 slots, 8 mm tape conversion).



## Large board handling capability

Maximum 1,240  $\times$  510 mm board can be handled (S20) without multi-staging the PCB for placement. Optional Max. 1,830  $\times$  510 mm board (S20) is available.





## Wide range component handling capability

01005 to max. 120 x 90 mm components can be handled by a single standard camera. 0201 (mm) ultra-tiny chip handling capability is also available as option. Max. component height is 30 mm (component height + board thickness), the largest in its class on the market.





## CFB/CTF full compatibility

The Feeder Bank Changer CFB-36, CFB-36E and newly developed CFB-45E as well as the Changeable Tray Feeder CTF-36C can be used on either the S10 and S20 with full backwards compatibility to the M10 and M20. Additionally CFB and CTF for the M10 and M20 are compatible with the new S10 and S20.

### **Auto-Nozzle-Changer Station**

ANC station can accommodate max. 24 nozzles. Another ANC station that can accommodate max. 40 nozzles is also available as option.







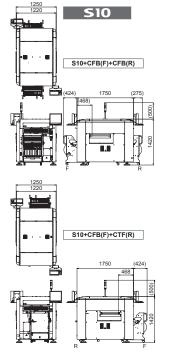
\* Fitted to S20 on the above pictures.

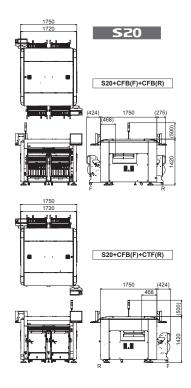
## **Options**

- 0201 mm chip handling capability
- Dispensed dot check function
- 3D-MID
- Rear fixed multi-scan camera
- F3 / F1 / F2 Rear 36-lane fixed feeder bank
- F3 45-lane fixed feeder bank
- Rear side switches
- Rear side operation system
- UPS4
- Conveyor extension, entrance/exit
- Component setup verifier
- Feeder relocatability
- Waste tape box

- Internal lighting
- Lead coplanarity sensor
- Safety cover, front/rear
- Clamp unit for CFB/CTF
- CFB-36E / CFB-45E F3 Electric Feeder Bank Changer
- CFB-36 F1/F2 Feeder Bank Changer
- CTF-36C Cassette type Changeable Tray Feeder
- FTF-36C Cassette type Fixed Tray Feeder
- RTS-1 Removable Tray Station
- Parts feeders
- Offline software
- iQvision

## External dimensions (mm)





<sup>\*</sup>Configurations on pictures may be different from standard ones.





Board size

#### **Specifications**

## i-PULSE S 10

(with input or output buffer used) (with input and output buffers used) Board thickness

(with buffer unused)

Board flow direction Board transfer speed

Placement speed (12 heads + 2 theta) Opt. Cond.

Placement accuracy A (μ+3σ) Placement accuracy B ( $\mu$ +3 $\sigma$ )

Placement angle

Z axis control / Theta axis control

Component height

Applicable components

Component package Drawback check

Screen language

Board positioning

Component types Transfer height

Machine dimensions, weight

Min. L50 x W30 mm to Max. L1.330 x W510 mm (Standard L955)

Min. I 50 x W 30 mm to Max. I 420 x W 510 mm

Min. L50 x W30 mm to Max. L330 x W510 mm

0.4 - 4.8 mm

Left to right (Std)

Max. 900 mm/sec

0.08 sec/CHIP (45,000CPH)

CHIP +/- 0.040 mm

IC +/- 0.025 mm

+/-180 degrees

AC servo motor

Max. 30 mm \*1 (Pre-placed components: max. 25 mm)

0201 mm - 120 x 90 mm, BGA, CSP, connector, etc.

8 - 56 mm tape (F1/F2 Feeders), 8 - 88 mm tape (F3 Electric Feeders), stick, tray

Vacuum check and vision check

English, Chinese, Korean, Japanese

Board grip unit, front reference, auto conveyor width adjustment

Max. 90 types (8 mm tape), 45 lanes x 2

900 +/- 20 mm

L1250 x D1750 x H1420 mm, Approx. 1,150 kg

### **Specifications**



Board size (with buffer unused)

(with input and output buffers used)

Board thickness Board flow direction

Board transfer speed

Placement speed (12 heads + 2 theta) Opt. Cond.

Placement accuracy A (μ+3σ)

Placement accuracy B (μ+3σ)

Placement angle

Z axis control / Theta axis control

Component height

Applicable components

Component package

Drawback check

Screen language

Board positioning

Component types

Transfer height Machine dimensions, weight

\*1 : Board thickness + Component height = Max 30mm

Min. L50 x W30 mm to Max. L1,830 x W510 mm (Standard L1,455)

L50 x W30 mm to Max. L540 x W510 mm

0.4 - 4.8 mm

Left to right (Std)

Max. 900 mm/sec

0.08 sec/CHIP (45,000 CPH)

CHIP +/- 0.040 mm

IC +/- 0.025 mm

+/-180 degrees

AC servo motor

Max. 30 mm \*1 (Pre-placed components: max. 25 mm)

0201 mm - 120 x 90 mm, BGA, CSP, connector, etc.

8 - 56 mm tape (F1/F2 Feeders), 8 - 88 mm tape (F3 Electric Feeders), stick, tray

Vacuum check and vision check

English, Chinese, Korean, Japanese

Board grip unit, front reference, auto conveyor width adjustment

Max 180 types (8 mm tape), 45 lanes x 4

900 +/- 20 mm

L1750 x D1750 x H1420 mm, Approx. 1450 kg

Some specifications and parts of the external appearance are subject to change without notice.

\*Under optimum conditions \*\*Under standard conditions as defined by Yamaha Motor

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